

Title (en)  
Electroplating method and electroplating apparatus

Title (de)  
Galvanisierungsverfahren- und Vorrichtung

Title (fr)  
Procédé et appareil de dépôt électrolytique

Publication  
**EP 1496142 A3 20060405 (EN)**

Application  
**EP 03257520 A 20031128**

Priority  
JP 2003192500 A 20030704

Abstract (en)  
[origin: EP1496142A2] The present invention provides a plating method and a plating apparatus capable of plating small parts effectively without any deformation. A object product to be plated is put in each accommodating concave portion in a carrier tape including a number of the accommodating concave portions spaced at a specific interval and this carrier tape is passed through a plating apparatus so as to form metallic plating layer on the surface of the object product to be plated.

IPC 8 full level  
**C25D 7/00** (2006.01); **C25D 17/28** (2006.01); **B65G 49/04** (2006.01); **C25D 5/00** (2006.01); **C25D 7/06** (2006.01); **C25D 17/00** (2006.01); **C25D 17/06** (2006.01); **C25D 17/16** (2006.01); **H01R 43/16** (2006.01)

CPC (source: EP US)  
**C25D 17/06** (2013.01 - EP US); **C25D 17/28** (2013.01 - EP US)

Citation (search report)

- [XAY] US 4321124 A 19820323 - AUDELO ALEXANDER P
- [YA] EP 1205411 A1 20020515 - STECKELBACH WILHELM [DE], et al
- [A] US 3898145 A 19750805 - DAVIS GERALD G, et al
- [A] EP 0501392 A2 19920902 - AMP INC [US]

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)  
**EP 1496142 A2 20050112; EP 1496142 A3 20060405; JP 2005023398 A 20050127; US 2005006243 A1 20050113**

DOCDB simple family (application)  
**EP 03257520 A 20031128; JP 2003192500 A 20030704; US 71758403 A 20031121**